







Release Date: 25 April 2023 Version: A1.1

PRODUCT DATASHEET



- ► PLCC6 Top View
- ➤ 3528 1.8t
- ► Red (622nm) / True Green (527nm) / Blue (468nm)

N0M63S62-2MA



3528 1.8t Series





Forward Current: 2/2/2mA*

Package: PLCC6 Top View Black Surface LED SMT Package

Forward Voltage (typ.): 1.9/2.4/2.7V

FEATURES (Red/Green/Blue):

Luminous Intensity (typ.): 50/125/28mcd@2mA

Colour: Red/Green/Blue Wavelength: 622/527/468nm **Viewing Angle: 120/120/120°**

Materials:

Die: AlGaInP-GaAs/InGaN/InGaN Resin: Epoxy (Water Clear) Operating Temperature: -40~+80°C Storage Temperature: -40~+85°C

Grouping Parameters:

- Forward voltage
- Luminous intensity
- Dominant wavelength
- Soldering Methods: Reflow soldering
- MSL Level: acc. to JEDEC Level 3
- Packing: 8mm tape with max.2000/reel, ø180mm (7")

* In the order of Red/Green/Blue.

APPLICATIONS:

3528 1.85t Series

- Indicator
- Dashboard
- 3C Application
- Display
- **Decoration Lighting**



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	l _F	30/30/30*	mA
Peak Forward Current Duty 1/8, f=1kHz	I _{FP}	125	mA
Reverse Voltage	VR	5	V
Reverse Current @5V	I _R	10	μА
Power Dissipation	P _D	75/93/102	mW
Operating Temperature	TOPR	-40~+100	°C
Storage Temperature	T _{STG}	-40~+100	°C

^{1. *} In the order of Red/Green/Blue.

Electrical & Optical Characteristics (Ta=25°C)

Darameter	Cumbal		Values		Lloit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V _F	1.7/2.2/2.5*	1.9/2.4/2.7	2.5/3.1/3.4	V	I _F =2mA
Luminous Intensity	I _V	50/125/16	80/200/28	125/320/40	mcd	I _F =2mA
Dominant Wavelength	λ_{D}	615/520/465	622/527/468	630/530/475	nm	I _F =2mA
Peak Wavelength	$\lambda_{ extsf{P}}$		630/520/465		nm	I _F =2mA
Spectral Line Half Bandwidth	Δλ		19/32/24		nm	I _F =2mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =2mA

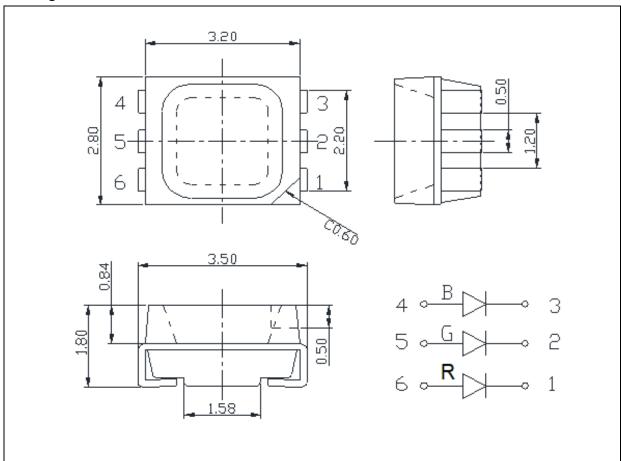
^{1. *} In the order of Red/Green/Blue.

^{2.} Luminous intensity (Iv) $\pm 15\%$, Forward Voltage (VF) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 5\%$.



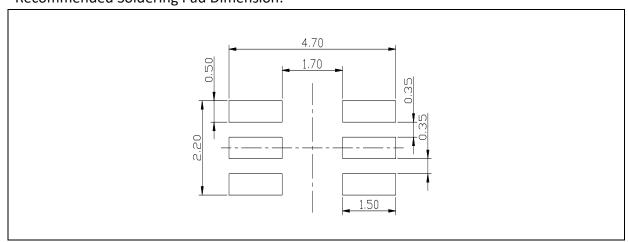
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications ($I_F = 2mA$):

	Code	Min.	Max.	Unit
Red		1.7	2.5	V
	d	2.2	2.5	
Green	е	2.5	2.8	V
	f	2.8	3.1	
	е	2.5	2.8	
Blue	f	2.8	3.1	V
	g	3.1	3.4	

Luminous Intensity Classifications (I_F = 2mA):

	Code	Min.	Max.	Unit
Red	G	50	63	mcd
	Н	63	80	
	1	80	100	
	J	100	125	
Green	K	125	160	mcd
	L	160	200	
	M	200	250	
	N	250	320	
Blue	В	16	20	mcd
	С	20	25	
	D	25	32	
	E	32	40	



BINNING GROUPS:

Wavelength Classifications ($I_F = 2mA$):

	Code	Min.	Max.	Unit
Red	S	615	620	
	u	620	625	nm
	V	625	630	
Green	U	520	522.5	nm
	V	522.5	525	
	W	525	527.5	
	X	527.5	530	
Blue	G	465	467.5	nm
	Н	467.5	470	
	I	470	472.5	
	J	472.5	475	

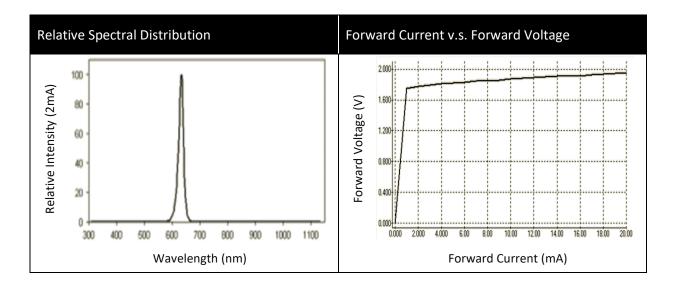
Example Group Name on Label:

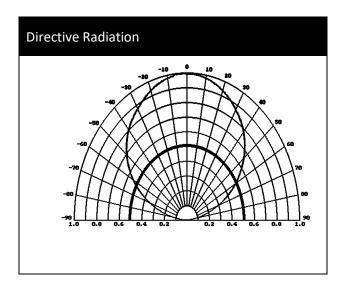
☐Ht gMW gEH 20 (in order of R/G/B):

- □Ht20 = □ (1.7~2.5V) ► H (63~80mcd) ► t (620~625nm) ► 20 (IF=2mA)
- gMW20 = g (3.1~3.4V) \blacktriangleright M (200~250mcd) \blacktriangleright W (525~527.5nm) \blacktriangleright 20 (IF=2mA)
- gEH20 = g (3.1~3.4V) ► E (32~40mcd) ► H (467.5~470nm) ► 20 (IF=2mA)



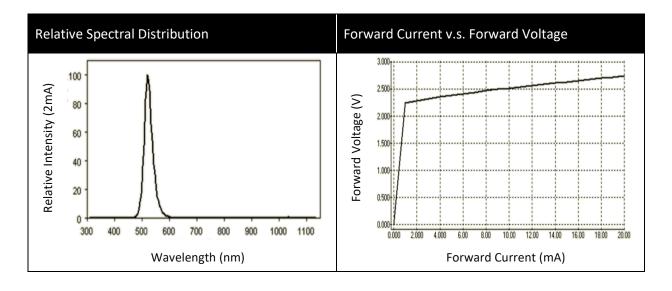
ELECTRO-OPTICAL CHARACTERISTICS (RED):

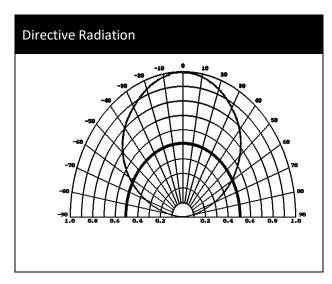






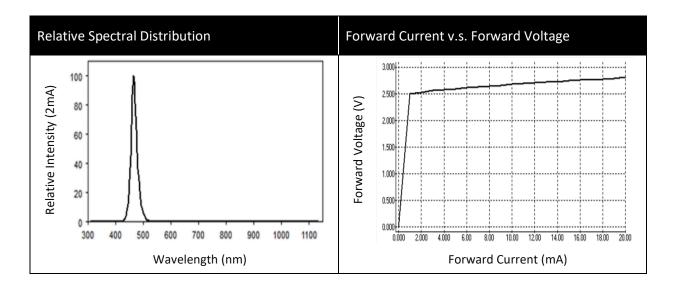
ELECTRO-OPTICAL CHARACTERISTICS (GREEN):

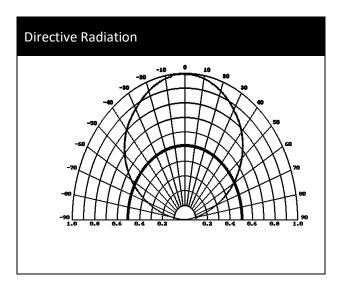






ELECTRO-OPTICAL CHARACTERISTICS (BLUE):

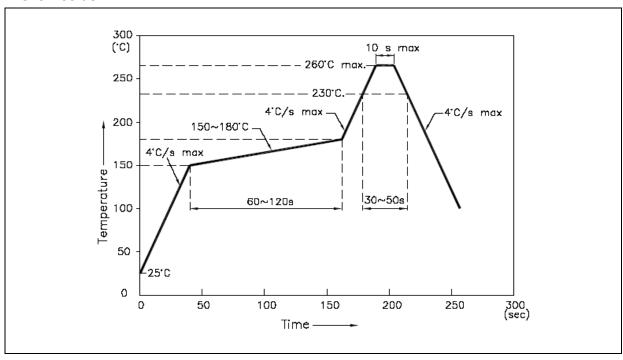






RECOMMENDED SOLDERING PROFILE:

Reflow Solder:



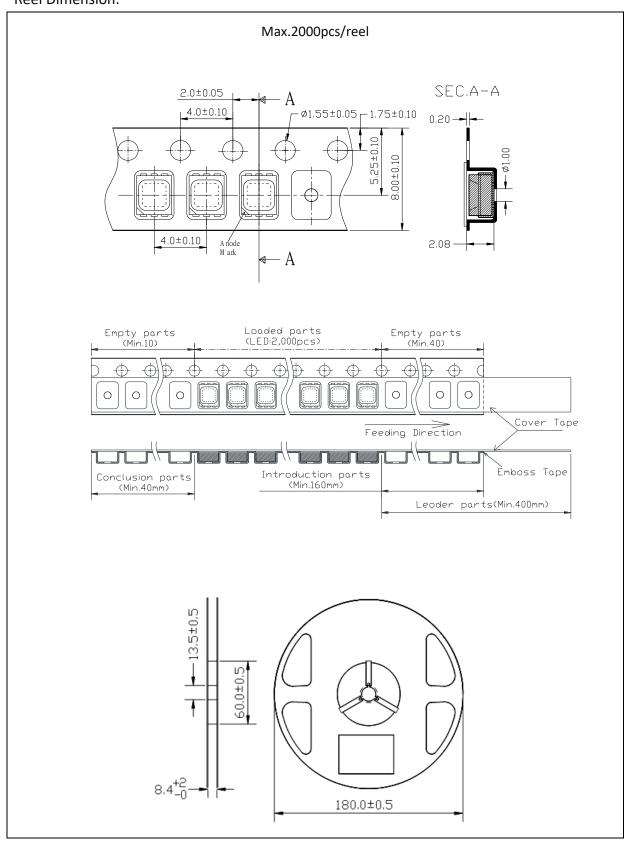
Note:

- 1. Recommend reflow temperature 245°C. The maximum soldering temperature should be limited to 260°C.
- 2. Maximum reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking at before use.

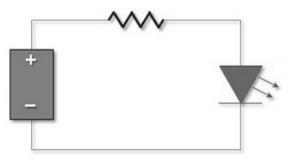
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light Blue) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	25/08/2021	Datasheet set-up.
A1.1	25/04/2023	New datasheet format.